



## Customized Adhesive Solutions

25 B Street Burlington MA 01803  
Phone: (978) 436-9600 Fax: (866) 788-7856  
Email: info@nextgenadhesives.com

# NGAC P910-27

# Technical Bulletin

## Low Shrinkage and Controlled Flow Adhesive

### **Description:**

NGAC P910-27 is low viscosity encapsulant designed for microelectronics applications requiring low shrinkage and high reliability performance.

### **Advantages and Applications:**

Uses include protecting wire bonds and bare die and other micro-electronic structural assembly applications. NGAC P910-27 is highly resistant to humidity and will withstand reflow temperatures up to 260C.

### **Storage Requirements:**

NGAC P910-27 is packaged in pre-mixed and frozen syringe. It must be shipped in dry ice\* and stored in a freezer. The optimum storage temperature is -60°C to -70°C and the minimum storage temperature recommended is -57°C.

\*Temperature during shipment should be maintained at -40°C or colder with dry ice.

### **Properties**

	<b>Typical Value</b>	<b>Test Method</b>
Color	Black	Visual
Specific Gravity	1.51	ASTM-D1875
Hardness Shore D	90	ASTM-D2240
Glass Transition, T <sub>g</sub>	130°C	ASTM-E1356
Operating Temperature:	-40 to 260°C	TP-305

### **Cure Schedule:**

Temperature	100°C	<b>PLUS</b>	150°C
Time	30 minutes		45 minutes

**OR**

Temperature	150°C
Time	45 minutes

\*\*\*Working life is subjective to application requirements.

For additional information or assistance, please call  
**978-436-9600**

All values reported above are typical values and are for reference use only. These values are not intended for use in developing specifications. Application testing under specific conditions should be performed to determine actual results and fitness for use.